

PART INFORMATION		
Mfg Item Number		MPC8250AVVPIBC
Mfg Item Name		TBGA 480 37.5SQ*1.7P1.27
SUPPLIER		
Company Name		Freescale Semiconductor Inc
Company Unique ID		14-141-7928
Response Date		2017-09-15
Response Document ID		5218K00080D048A1.32
Contact Name		Freescale Semiconductor Inc
Contact Title		Product Technical Support
Contact Phone		1-800-521-6274
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Authorized Representative		Daniel Binyon
Representative Title		EPP Customer Response
Representative Phone		512-895-3406
Representative Email		eppanlst@freescale.com
URL for Additional Information		www.freescale.com
DECLARATION		
EU RoHS		Yes
Pb Free		Yes
HalogenFree		Yes
Plating Indicator		e1
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number		MPC8250AVVPIBC
Mfg Item Name		TBGA 480 37.5SQ*1.7P1.27
Version		ALL
Weight		10.060850
UoM		g
Unit Volume		EACH
J-STD-020 MSL Rating		3
Peak Processing Temperature		260 C
Max Time at Peak Temperature		40 seconds
Number of Processing Cycles		3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0313						g					
Epoxy Die Attach		Solvents, additives, and other materials	1,3,5-Triazine-2,4-diamine, 6-[2-(2-methyl-1H-imidazol-1-yl)ethyl]	38668-46-1		0.00026452	g	8451	0.8451		26	0.0026
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00405582	g	129579	12.9579		403	0.0403
Epoxy Die Attach		Plastics/polymers	4,4'-Dihydroxydiphenyl	92-88-6		0.00026452	g	8451	0.8451		26	0.0026
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.02671514	g	853519	85.3519		2655	0.2655
Dam	0.018						g					
Dam		Solvents, additives, and other materials	Methylhexahydrophthalic anhydride	25550-51-0		0.00114707	g	63726	6.3726		114	0.0114
Dam		Solvents, additives, and other materials	Substituted phthalic anhydride	34090-76-1		0.00114707	g	63726	6.3726		114	0.0114
Dam		Plastics/polymers	2,2'-(1,1-methylethyldene)bis[4,1-phenyleneoxyethylene]bisoxirane	1675-54-3		0.00104726	g	58181	5.8181		104	0.0104
Dam		Plastics/polymers	3,4-Epoxy-cyclohexanecarboxylic acid (3,4-epoxycyclohexylmethyl) ester	2386-67-0		0.00104726	g	58181	5.8181		104	0.0104
Dam		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00007578	g	4210	0.421		7	0.0007
Dam		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.00038826	g	21570	2.157		38	0.0038
Dam		Glass	Cristobalite	14464-46-1		0.00007112	g	3951	0.3951		7	0.0007
Dam		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.01307618	g	726455	72.6455		1299	0.1299
Die Encapsulant, Filler	0.2854						g					
Die Encapsulant, Filler		Solvents, additives, and other materials	Methylhexahydrophthalic anhydride	25550-51-0		0.04064381	g	142410	14.241		4039	0.4039
Die Encapsulant, Filler		Antimony/Antimony Compounds	Antimony pentoxide	1314-60-9		0.00043352	g	1519	0.1519		43	0.0043
Die Encapsulant, Filler		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00046064	g	1614	0.1614		45	0.0045
Die Encapsulant, Filler		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.04064381	g	142410	14.241		4039	0.4039
Die Encapsulant, Filler		Glass	Silica, vitreous	60676-86-0		0.20321822	g	712047	71.2047		20198	2.0198
Bonding Wire	0.0312						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0312	g	1000000	100		3101	0.3101
Silicon Semiconductor Die	0.06005						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.001201	g	20000	2		119	0.0119
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.058849	g	980000	98		5849	0.5849
Solder Balls - Lead Free	0.8166						g					
Solder Balls - Lead Free		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.00000572	g	7	0.0007		0	0
Solder Balls - Lead Free		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000572	g	7	0.0007		0	0
Solder Balls - Lead Free		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00000408	g	5	0.0005		0	0
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.0057162	g	7000	0.7		568	0.0568
Solder Balls - Lead Free		Metals	Iron, metal	7439-89-6		0.0000147	g	18	0.0018		1	0.0001
Solder Balls - Lead Free		Lead/Lead Compounds	Lead	7439-92-1		0.00004573	g	56	0.0056		4	0.0004
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.03070416	g	37600	3.76		3051	0.3051
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.78010369	g	955307	95.5307		77538	7.7538
Organic Substrate	8.8183						g					
Organic Substrate		Metals	Aluminum fluoride	7784-18-1		0.02245139	g	2546	0.2546		2231	0.2231
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.03188697	g	3616	0.3616		3169	0.3169
Organic Substrate		Metals	Chromium, metal	7440-47-3		0.00000882	g	1	0.0001		0	0
Organic Substrate		Metals	Copper, metal	7440-50-8		8.40452774	g	953078	95.3078		835389	83.5389
Organic Substrate		Metals	Cupric oxide	1317-38-0		0.1232622	g	13978	1.3978		12251	1.2251
Organic Substrate		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl diglycidyl ether	85954-11-6		0.04370349	g	4956	0.4956		4343	0.4343
Organic Substrate		Metals	Gold, metal	7440-57-5		0.00149029	g	169	0.0169		148	0.0148
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.00947967	g	1075	0.1075		542	0.0542
Organic Substrate		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.04529961	g	5137	0.5137		4502	0.4502
Organic Substrate		Metals	Zinc, metal	7440-66-6		0.00004409	g	5	0.0005		4	0.0004
Organic Substrate		Metals	Zirconium, metal	7440-67-7		0.0031568	g	376	0.0376		329	0.0329
Organic Substrate		Solvents, additives, and other materials	Morpholin	110-91-8		0.00354496	g	402	0.0402		352	0.0352
Organic Substrate		Plastics/polymers	Formaldehyde, polymer with 4,4'-(1,1-methylethyldene)bis[phenol]	25085-75-0		0.00740737	g	840	0.084		736	0.0736
Organic Substrate		Plastics/polymers	Polyethylene terephthalate	25038-69-9		0.03780405	g	4287	0.4287		3757	0.3757
Organic Substrate		Glass	Silica amorphous	61790-63-2		0.00354496	g	402	0.0402		352	0.0352
Organic Substrate		Plastics/polymers	Polyamide 6	63428-83-1		0.00865075	g	961	0.0961		859	0.0859
Organic Substrate		Plastics/polymers	Poly[[1,1':3,3'-tetrahydro-1,1':3,3'-tetraoxo[5,5'-bi-2H-isindole]2,2'-diyl]-1,4-phenylene]	32197-39-0		0.07036767	g	7962	0.7962		6996	0.6996
Organic Substrate		Solvents, additives, and other materials	3,6,9,12-Tetraazatetradecane-1,14-diamine	4067-16-7		0.00149029	g	169	0.0169		148	0.0148

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPC8250AVVPIBC_IPC1752_v11.xml

http://www.freescale.com/mcds/MPC8250AVVPIBC_IPC1752A.xml